

Version with Markings to Show Changes Made

The specification has been amended as follows:

At page 1, after the title, the following paragraph has been inserted:

--This application is a divisional of U.S. Patent Application Serial No. 09/606,583, filed on June 29, 2000 by Mark Kenneth Hoffmeyer et al. and entitled "PROCESSING OF CIRCUIT BOARDS WITH PROTECTIVE, ADHESIVE-LESS COVERS ON AREA ARRAY BONDING SITES," the disclosure of which is incorporated by reference herein.--

The claims have been amended as follows:

Claims 1-10 and 13-18 have been canceled.

Claims 11-12 and 19-22 remain and are currently pending as follows:

11. An assembly comprising:

a circuit board;

an area array bonding site on a surface of the circuit board; and

a protective cover overlaying the bonding site, the protective cover removably registered to the bonding site by a plurality of posts secured to one of the protective cover and the circuit board into a plurality of apertures disposed in the other of the protective cover and the circuit board.

12. The assembly of claim 11, wherein the protective cover includes an adhesiveless surface contacting the bonding site.

19. A cover for protecting an area array bonding site on a surface of a circuit board, the circuit board having a plurality of apertures, the cover comprising:
a base member having a first face and second face, the base member shaped to at

1 least correspond to said area array bonding site; and
2 a plurality of posts coupled to the first face and registered for said plurality of
3 apertures.

1 20. The cover of claim 19, wherein the first face of the base member further includes
2 a recess corresponding to said area array bonding site.

1 21. The cover of claim 19, further comprising:
2 a graspable extension coupled to the second face of the base member.

1 22. The cover of claim 19, wherein each of the plurality of posts includes a diametral
2 slot.